

## GaAs MMIC Frequency Multiplier Chip, 20-40GHz

### Performance characteristics

- Output frequency range: 20 - 40GHz
- Typical power output : 17.5dBm
- Typical input power: -2dBm
- Working voltage: +5V/100mA
- 50Ohm input/output
- 100% on-chip testing
- Chip size : 1.68 x 1.62 x 0.1mm

### Product Introduction

GL-2040-2E is an active doubler chip. When the input signal power is -2 dBm , the output signal power in the range of 20 GHz to 40 GHz is 17.5 dBm. The chip through-hole metallization process ensures good grounding, and the back side is metallized, which is suitable for eutectic sintering or conductive adhesive bonding process .

#### Use restriction parameter <sup>1</sup>

Maximum input power	+20dBm
Maximum working range	+ 8V
Operating temperature	-55 ~ +85°C
storage temperature	-65 ~ +150°C

【1】 Exceeding any of these maximum limits may cause permanent damage.

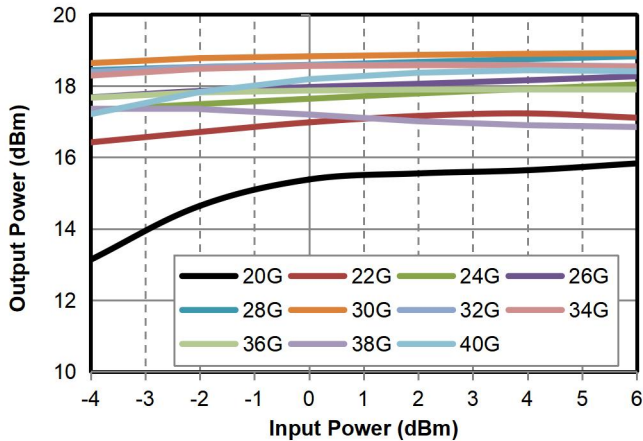
#### Electrical performance parameters ( TA = +25°C , Vdd = +5V, Pin = -2dBm )

index	Minimum	Typical Value	Maximum	unit
Input frequency range	10-20			GHz
Output frequency range	20-40			GHz
Output Power	-	17.5	-	dBm
Fundamental Suppression	-	23	-	dBc
Input return loss	-	17	-	dB
Output return loss	-	13	-	dB
Current	100			mA

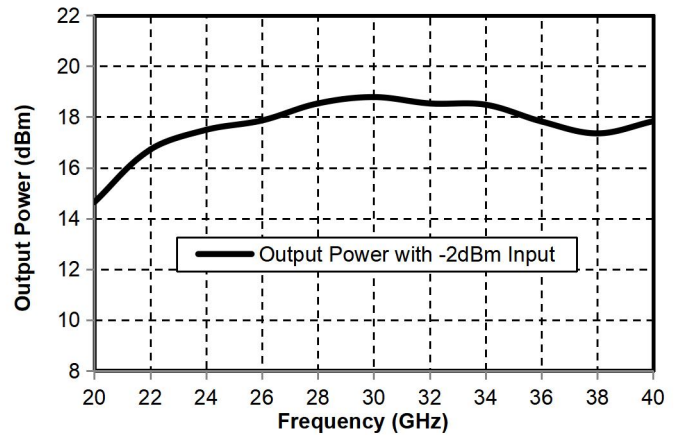
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Main index test curve

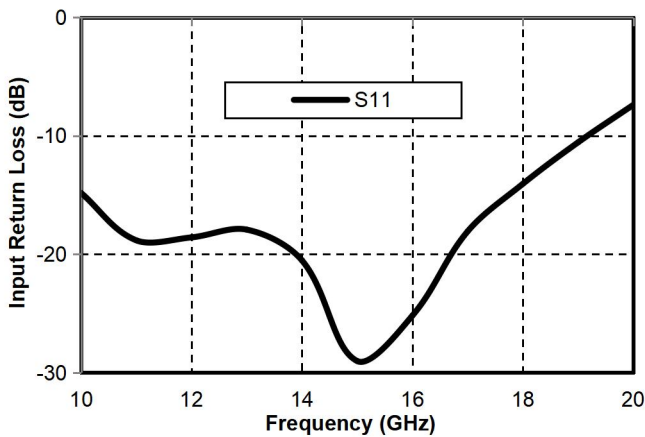
Output Power vs. Input Power



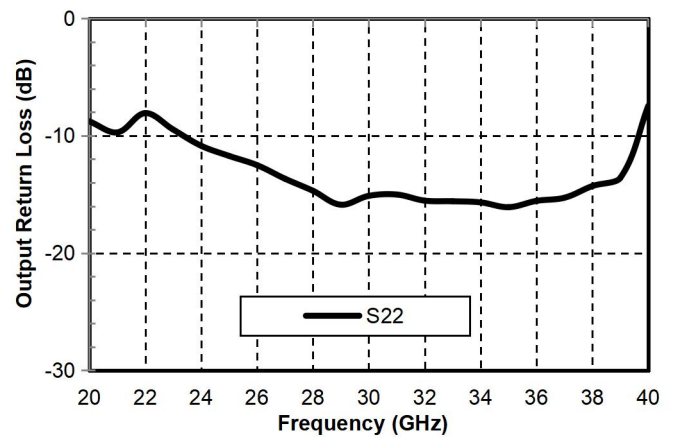
Output power vs. frequency @Pin=-2dBm



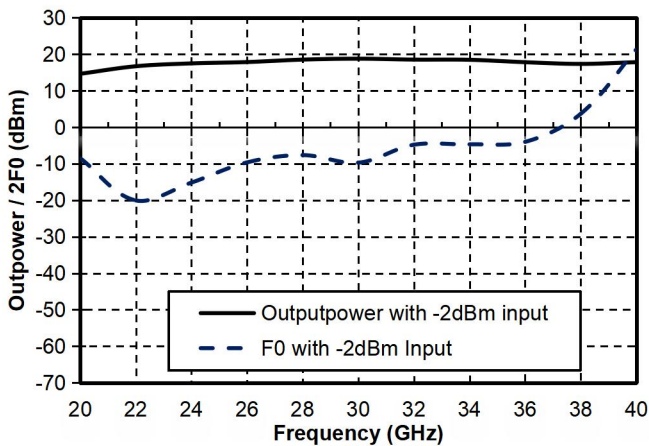
Input Return Loss vs. Operating Frequency



Output Return Loss vs. Operating Frequency

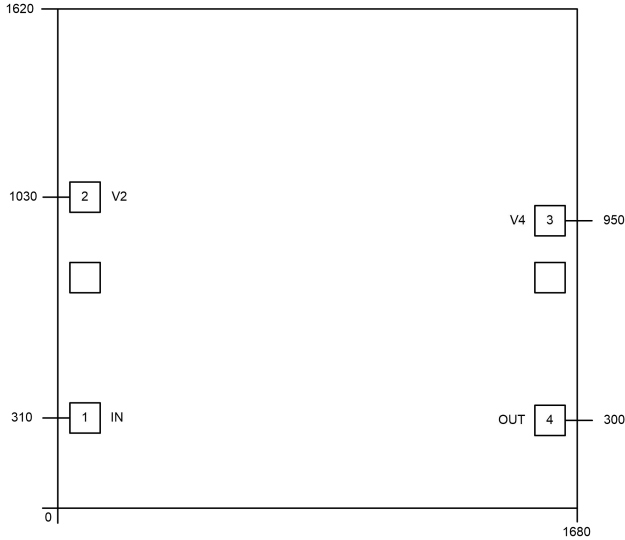


Fundamental Wave vs. Output Power



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Appearance structure <sup>2</sup>



【2】 The units in the figure are all micrometers (dimensional tolerance:  $\pm 100\mu\text{m}$  )

### Bonding point definition

Bonding point number	Function Symbol	Functional Description
1	RFIN	RF signal input terminal
4	RF OUT	RF signal output terminal
2.3*	Vd2, Vd3	Amplifier drain bias, external 100pF , 1000pF bypass capacitor required
Chip bottom	GND	The bottom of the chip needs to be well grounded to RF and DC

\*Requires both sides to be powered on simultaneously.

### Recommended assembly drawing

